



SOT341-1

plastic shrink small outline package; 28 leads; body width 5.3 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP28
Package type industry code	SSOP28
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-150
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

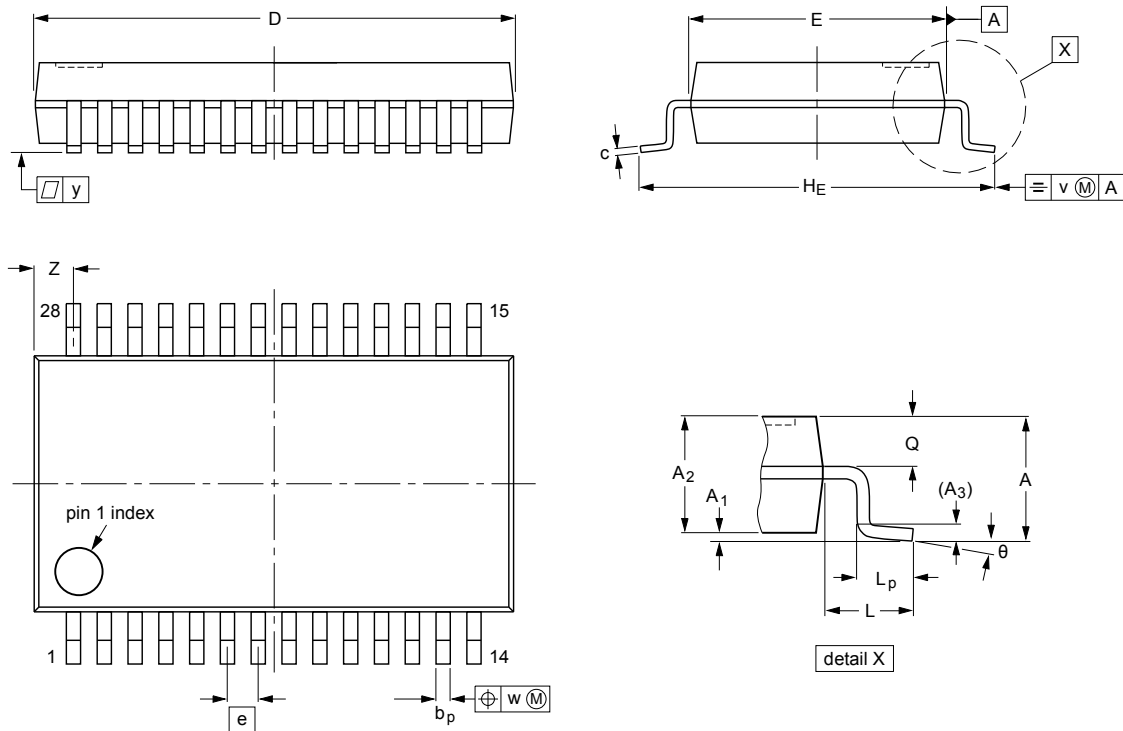
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10	-	10.2	10.4	mm
E	package width	5.2	-	5.3	5.4	mm
A	seated height	[tbd]	-	2	2	mm
A ₂	package height	1.65	-	1.73	1.8	mm
n ₂	actual quantity of termination	-	-	28	-	



2. Package outline

SSOP28: plastic shrink small outline package; 28 leads; body width 5.3 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	10.4 10.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.1 0.7	8° 0°

Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT341-1		MO-150			99-12-27 03-02-19

Fig. 1. Package outline SSOP28 (SOT341-1)

3. Soldering

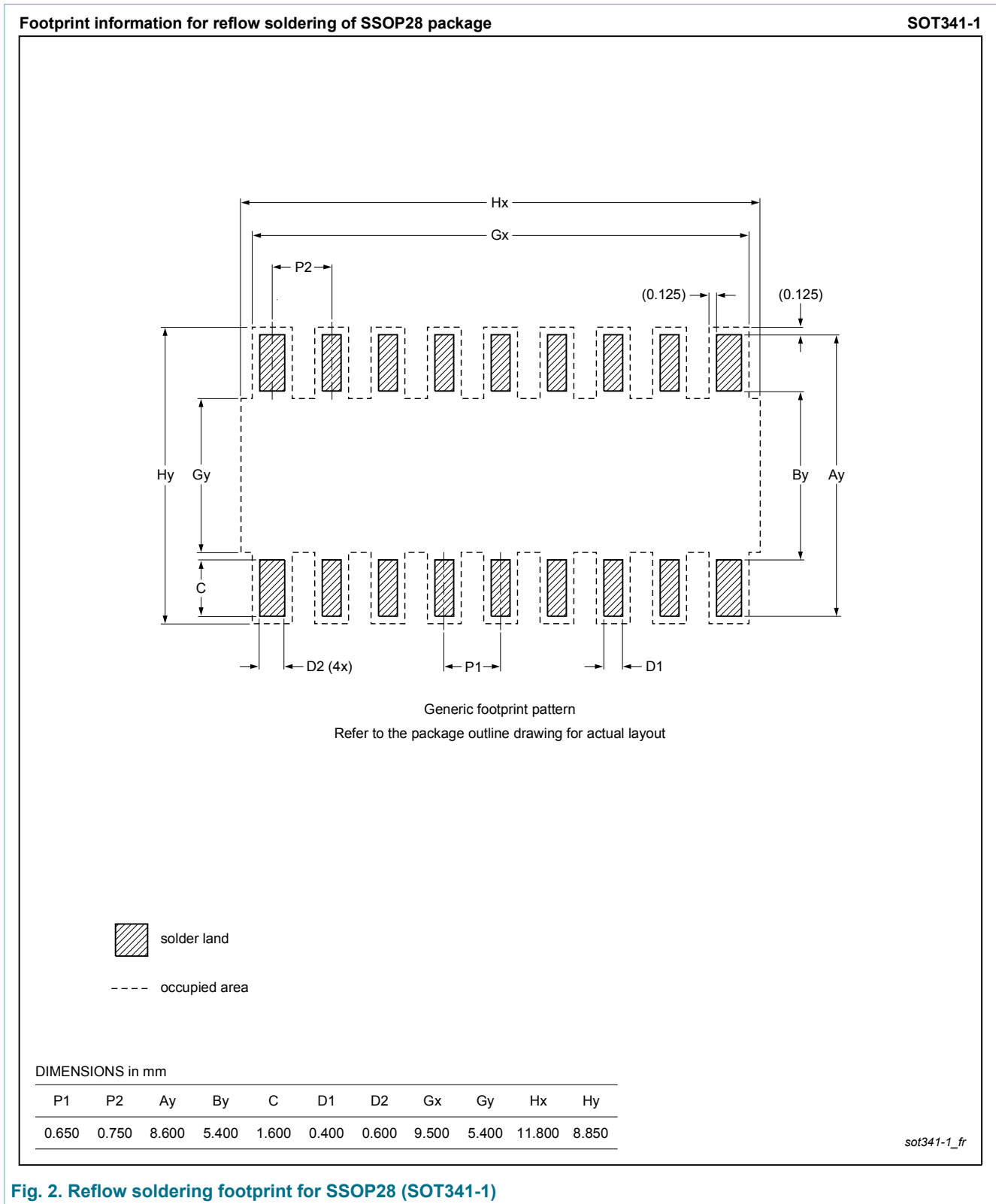


Fig. 2. Reflow soldering footprint for SSOP28 (SOT341-1)

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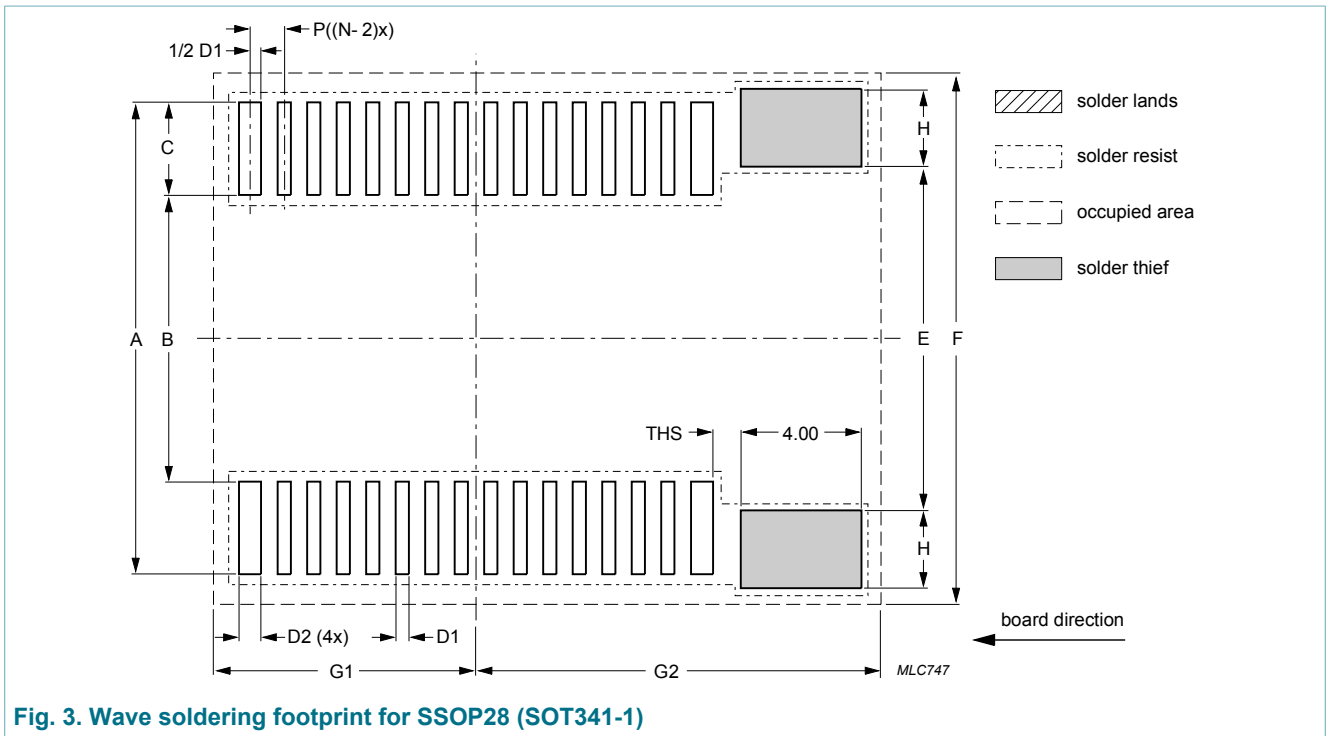


Fig. 3. Wave soldering footprint for SSOP28 (SOT341-1)

4. Legal information

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